

# 第三章 表面组装元器件

IC



IC  
IC PCB  
IC



IC  
IC



IC

IC Integrated Circuit

IC

IC

BGA Ball Grid Array

QFP Quad Flat Package

SOP Small Outline Package

( )

PLCC Plastic Leaded Chip Carrier  
)

( " J"

SOJ Small Outline J-Leaded Package  
)

J

( " J"

QFN Quad Flat No Lead Package)

LCC

CSP Chip Scale Package)

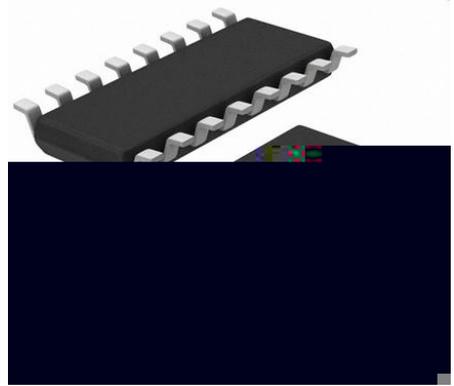
# IC



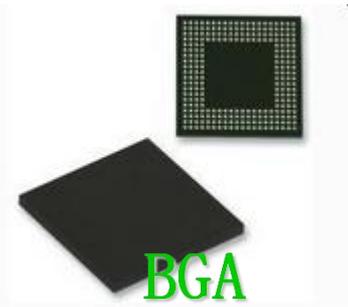
PLCC



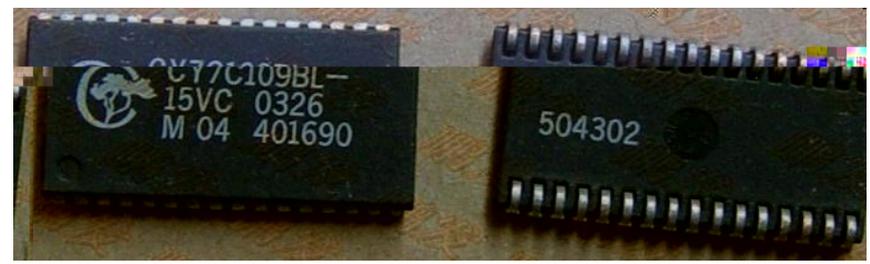
QFP



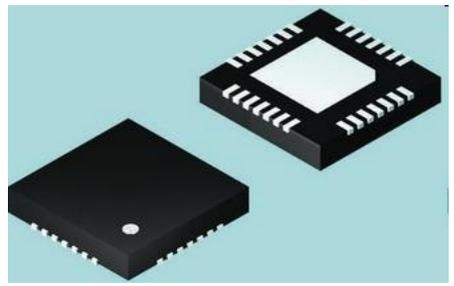
SOP



BGA

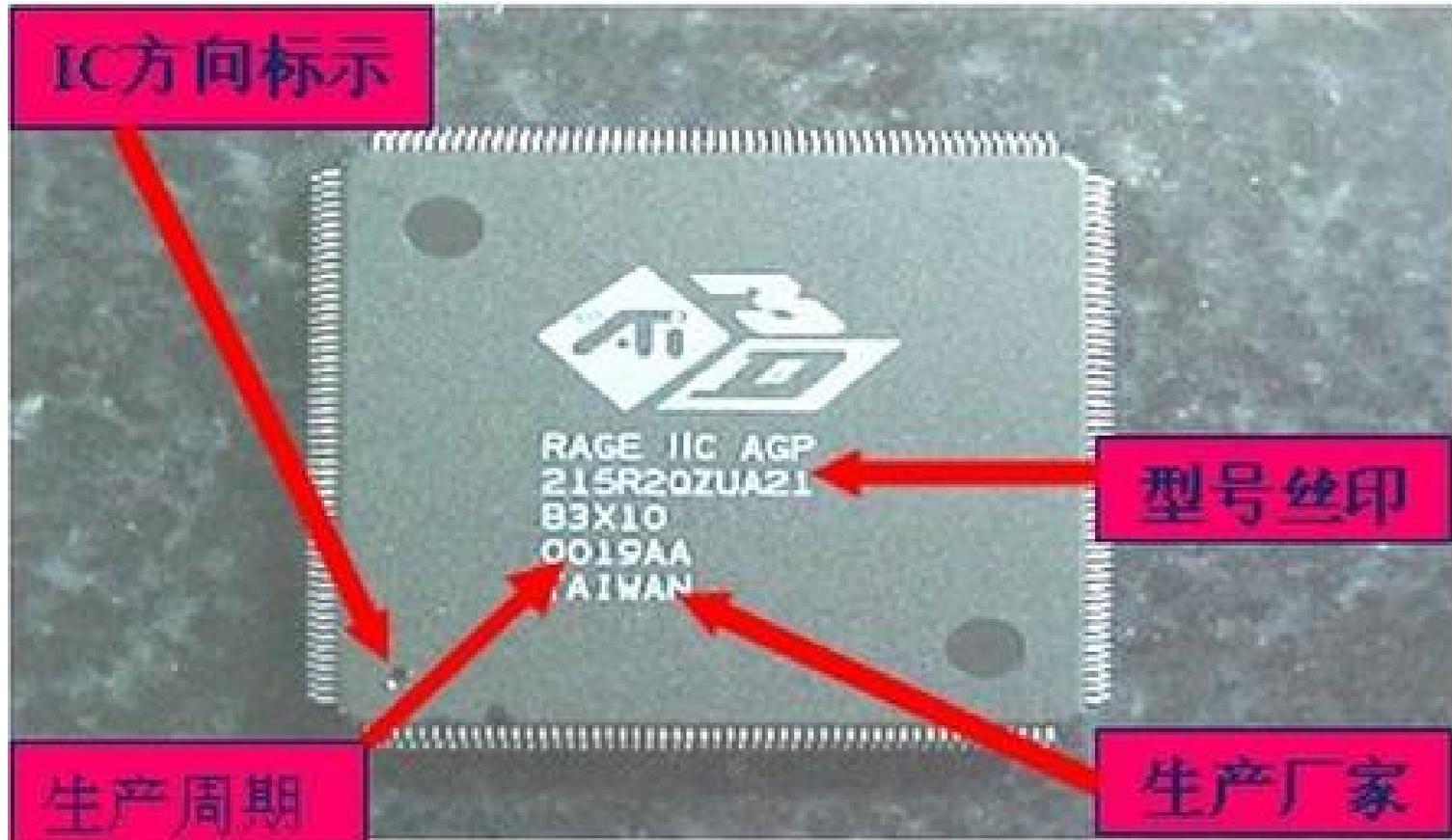


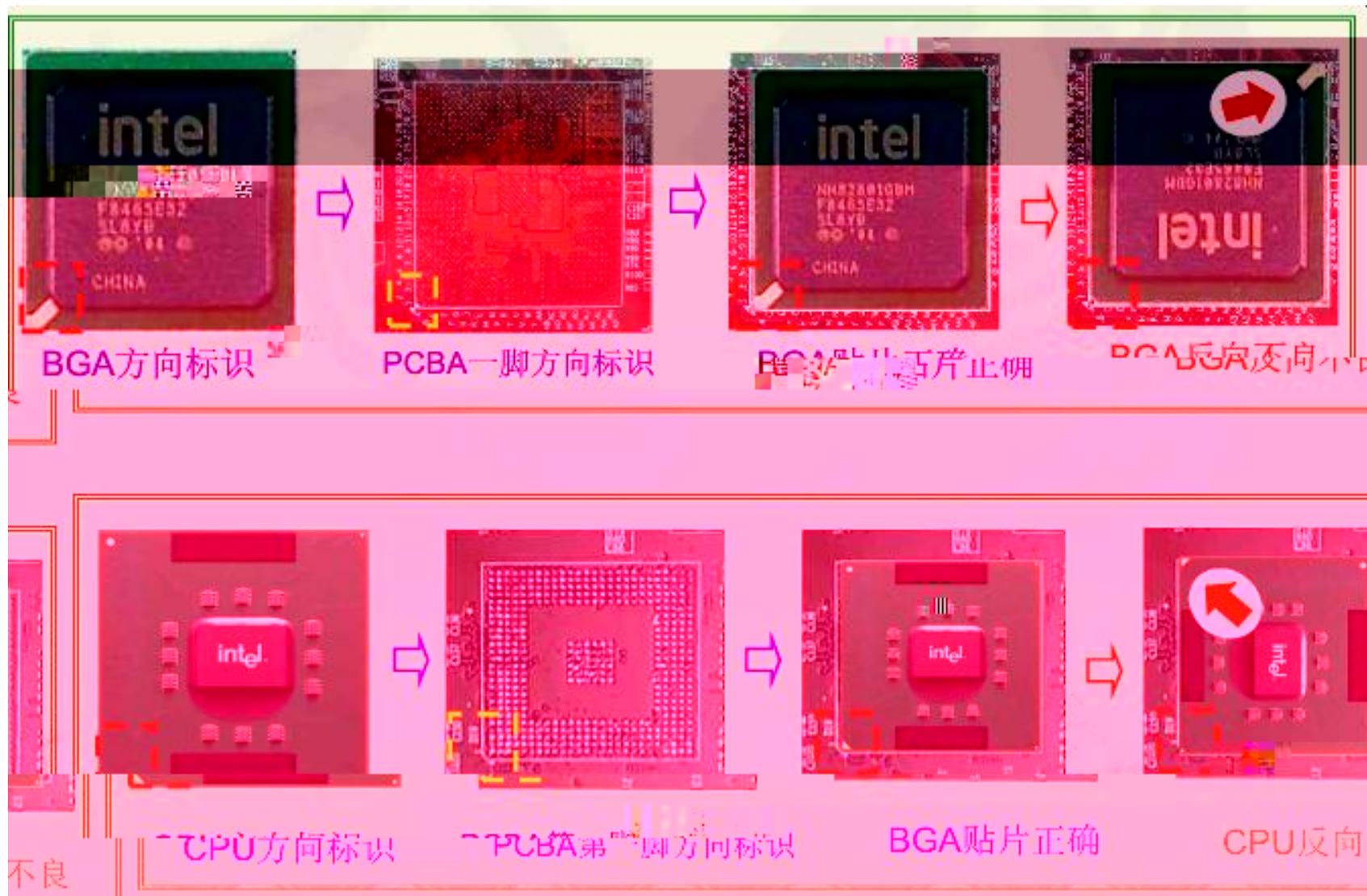
SOJ

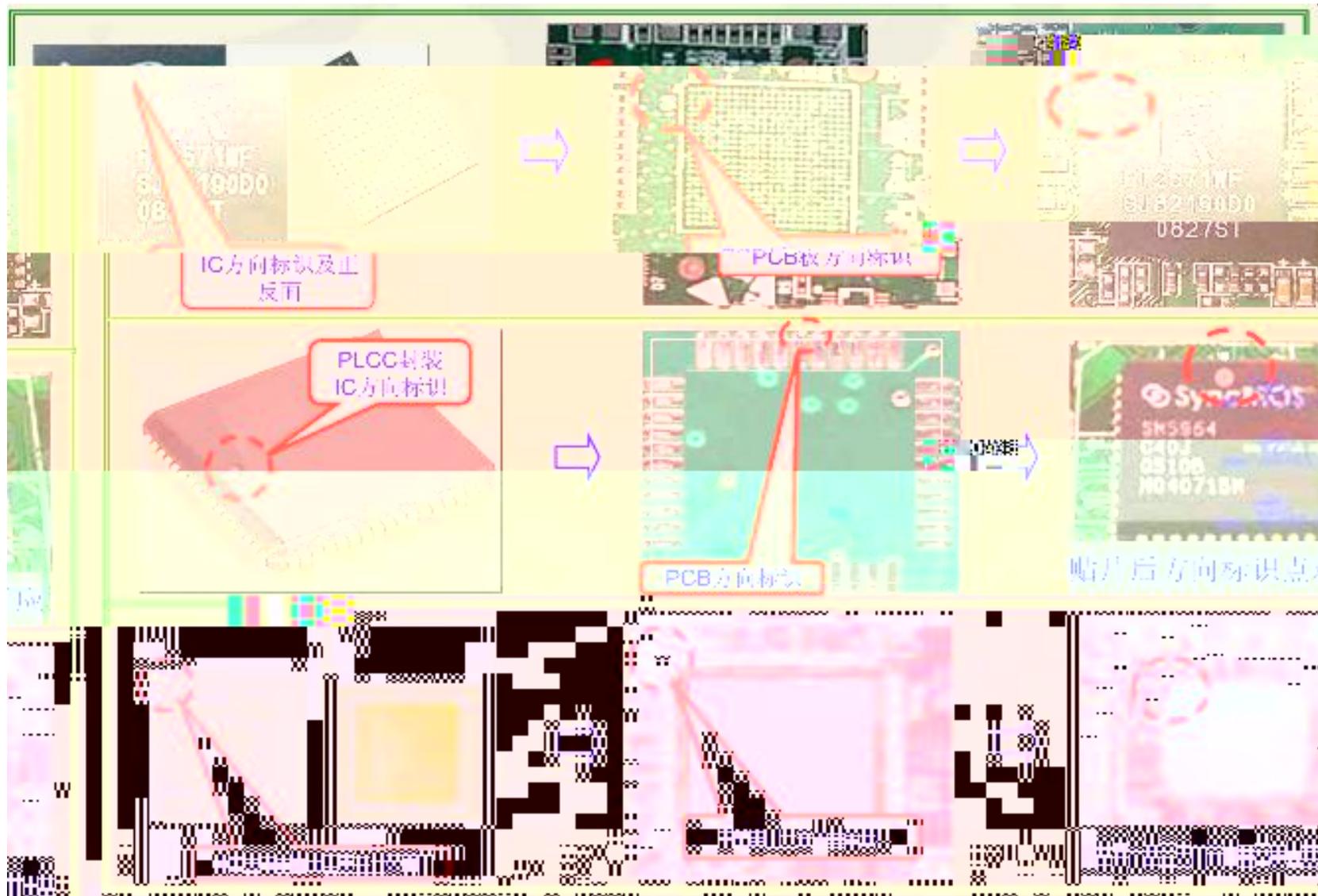


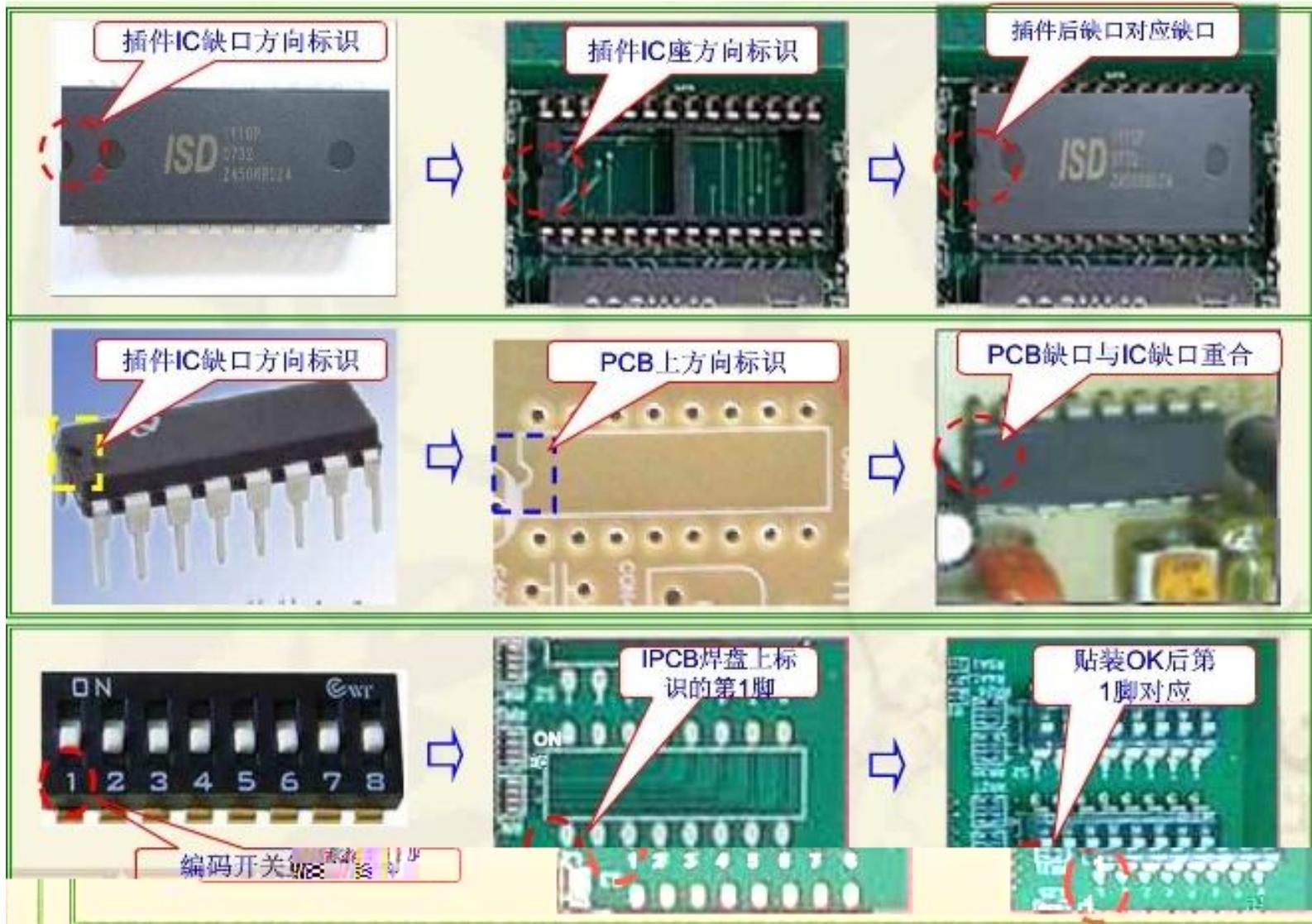
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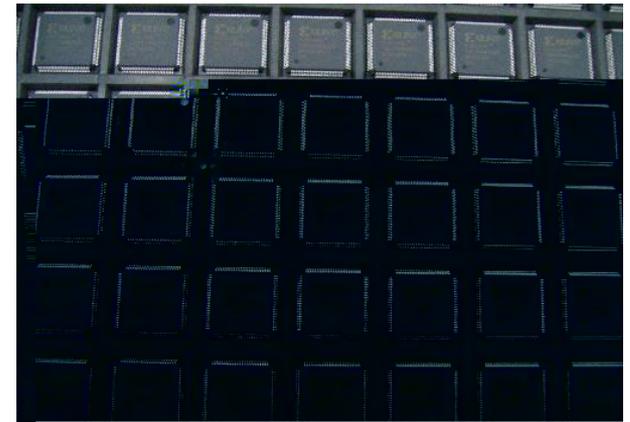
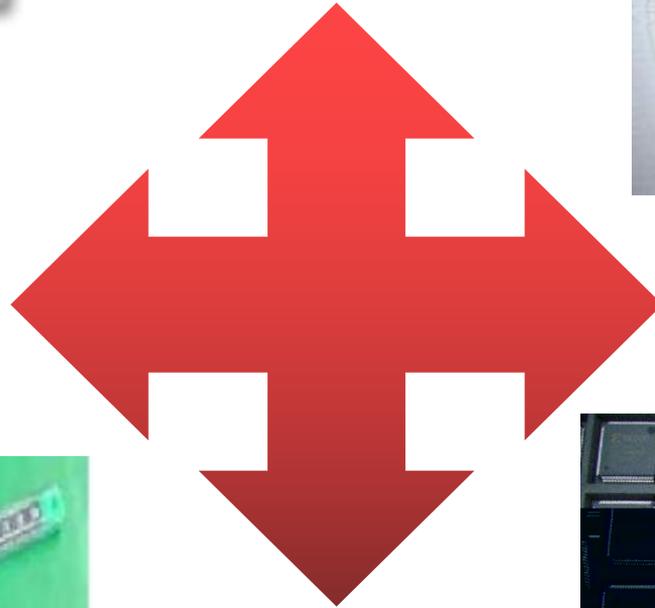
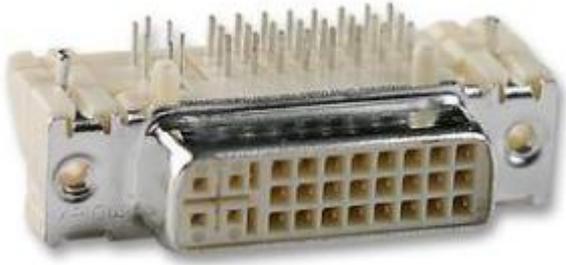
# IC





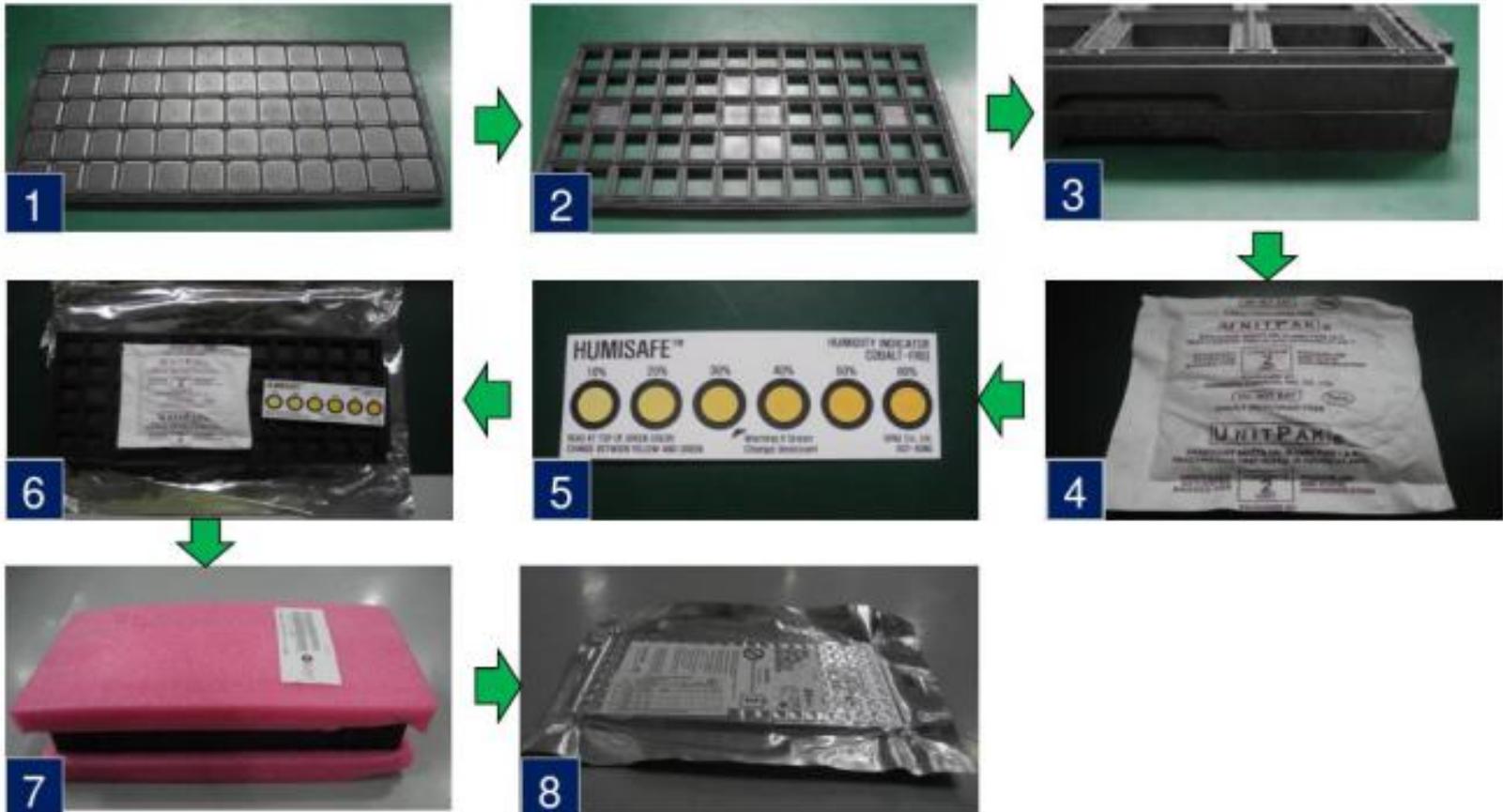




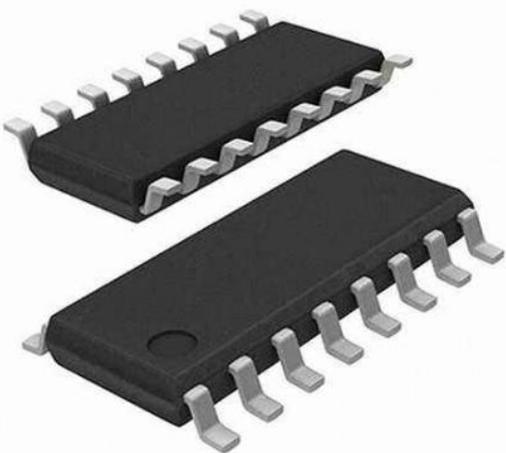
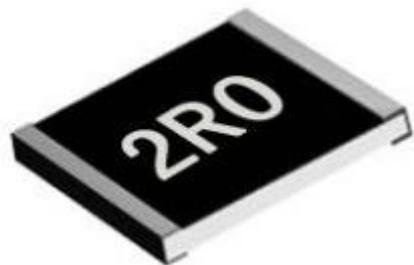


描述：正确Tray包装图片展示

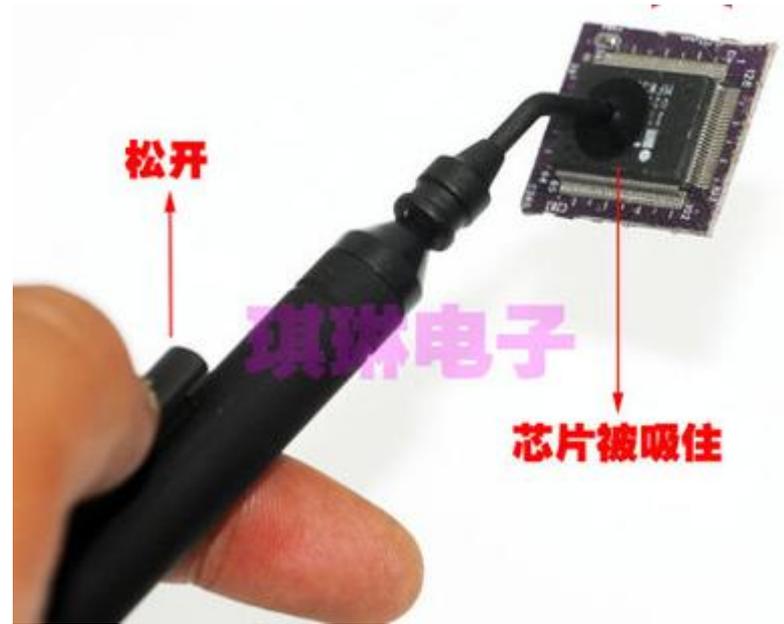
Tray (IC) + Tray上盖 + 干燥剂 + 湿度标示卡 + 防静电袋 + 防护泡棉 + 防静电真空包装 = 正规包装方式

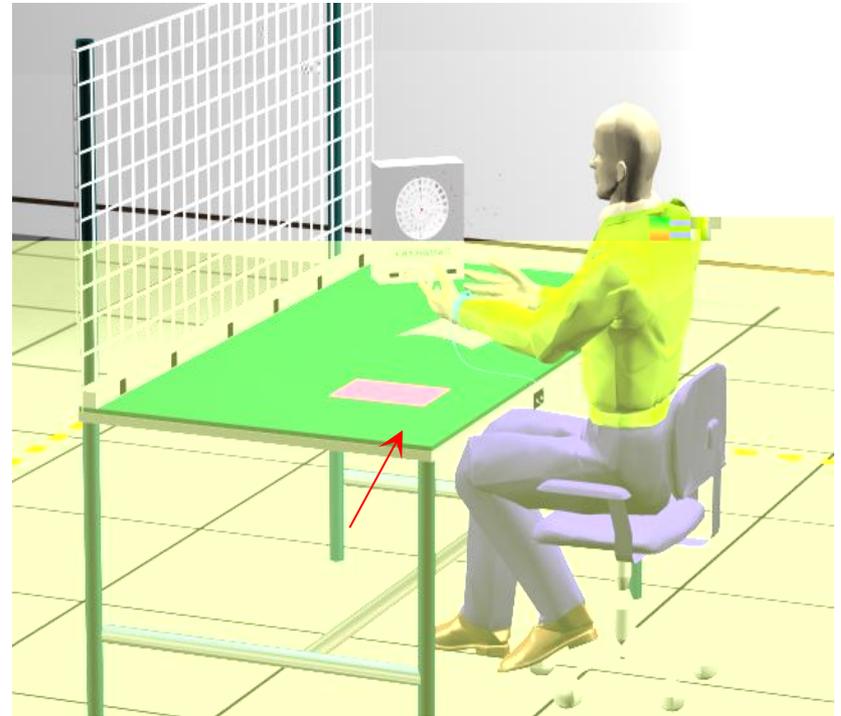
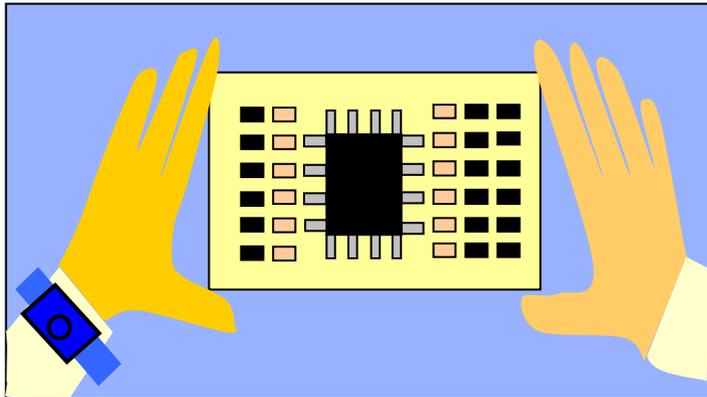
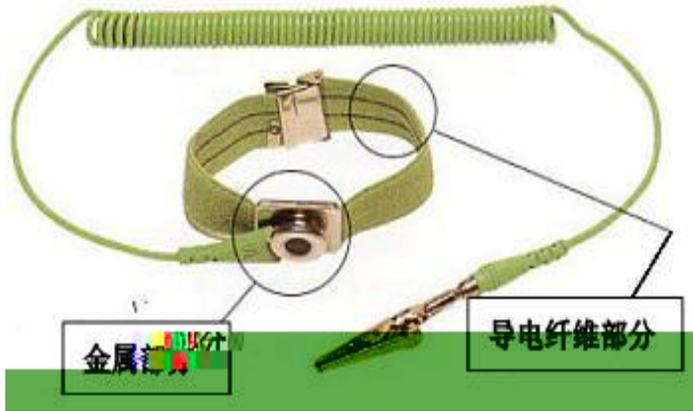


## 装配适应性

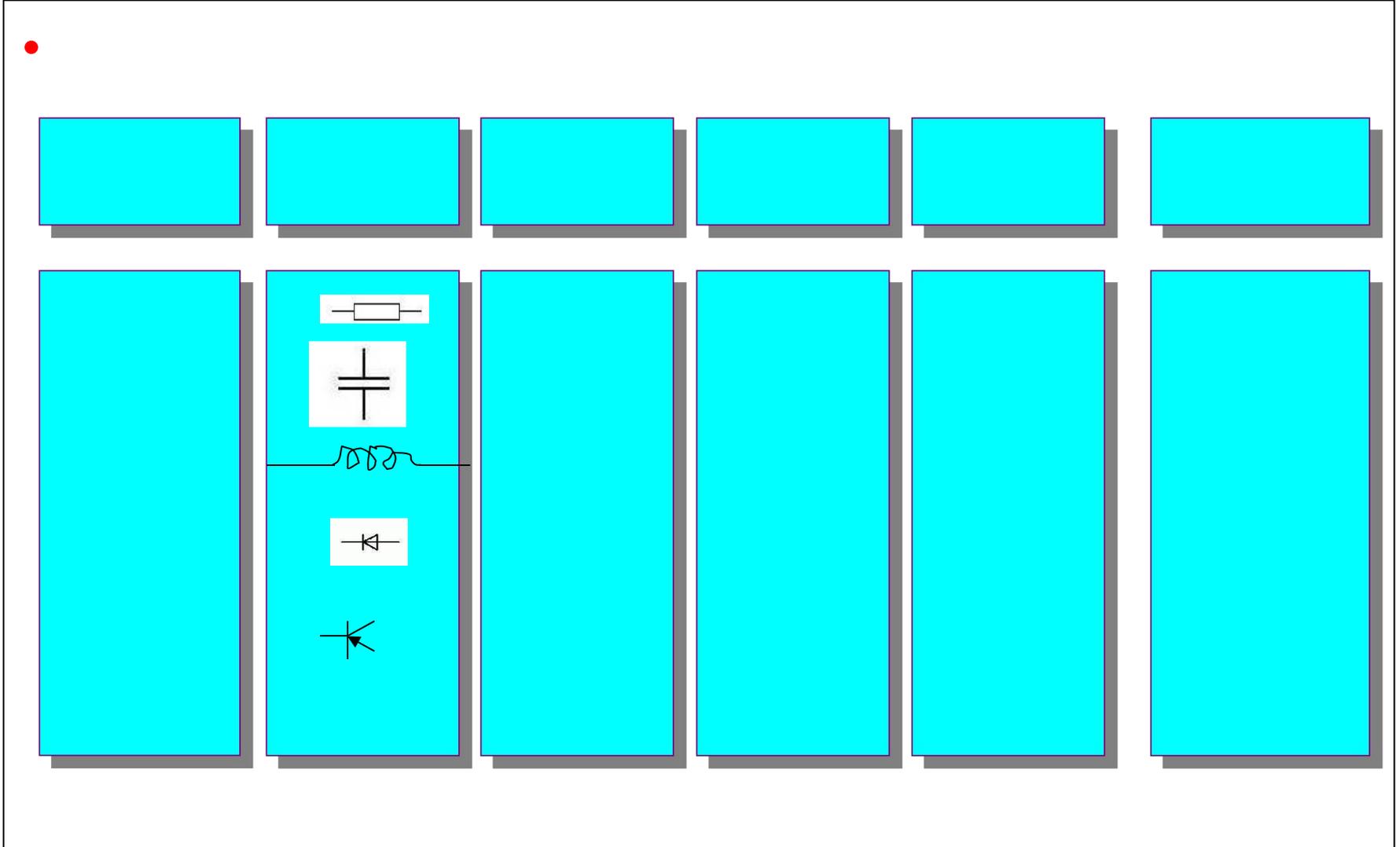









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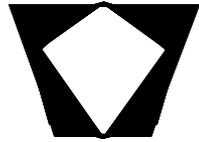
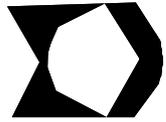


- 4.7M = -----K = -----
- 560 = -----K = -----M
- 320K = ----- = -----M







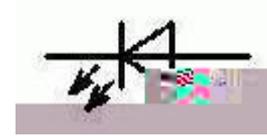
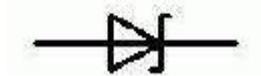


560uF =

nF =

m

1



2

3.

100nH =

$\mu$  H =

H

5600 $\mu$  H =

nH =

mH

4.

